



# DZ3J056D0L

## Silicon epitaxial planar type

For surge absorption circuit  
 DZ3X056D in SMini3 type package

### ■ Features

- Excellent rising characteristics of zener current I<sub>Z</sub>
- Low zener operating resistance R<sub>Z</sub>
- Halogen-free / RoHS compliant  
 (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

### ■ Marking Symbol: 0W

### ■ Packaging

Embossed type (Thermo-compression sealing) 3 000 pcs / reel (standard)

### ■ Absolute Maximum Ratings Ta = 25 °C

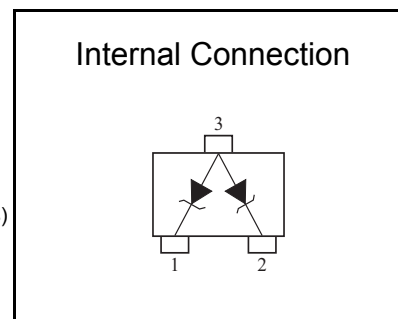
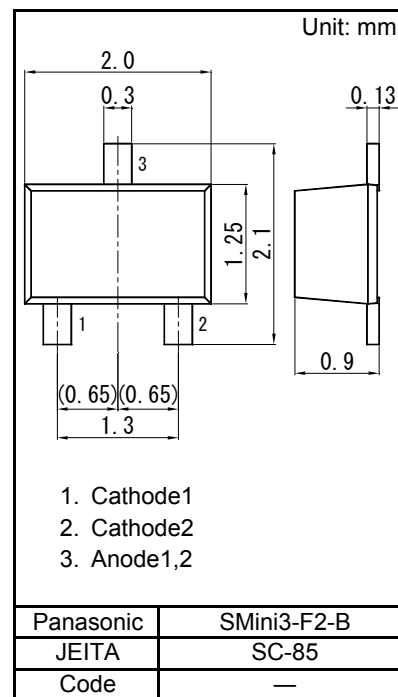
Parameter	Symbol	Rating	Unit
Total power dissipation <sup>*1</sup>	PT	150	mW
Electrostatic discharge <sup>*2</sup>	ESD	±10	kV
Junction temperature	T <sub>j</sub>	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C

Note) \*1: Mounted on glass epoxy print board. ( 45 mm x 45 mm x 1 mm)

(2 Diode total)

Solder in ( 0.9 mm x 0.8 mm)

\*2: Test method: IEC61000\_4\_2(C = 150 pF, R = 330 Ω, Contact discharge: 10 times)



### ■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	VF	IF = 10 mA			1.0	V
Zener voltage <sup>*1,*2</sup>	VZ	IZ = 5 mA	5.32		5.88	V
Zener operating resistance	RZ	IZ = 5 mA			40	Ω
Zener rise operating resistance	RZK	IZ = 0.5 mA			200	Ω
Reverse current	IR	VR = 2.5 V			0.5	μA
Temperature coefficient of zener voltage <sup>*3</sup>	SZ	IZ = 5 mA		2.0		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

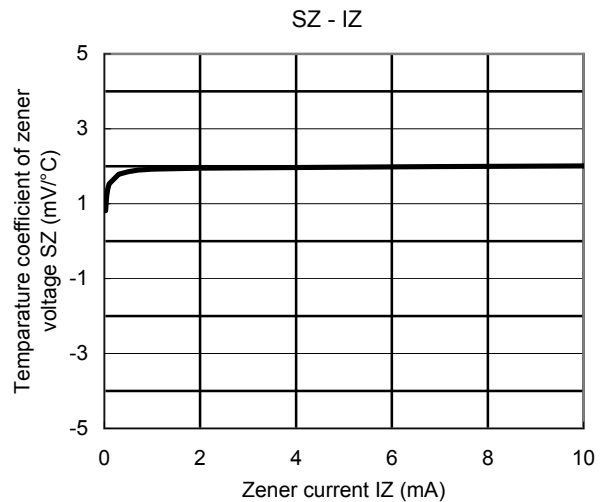
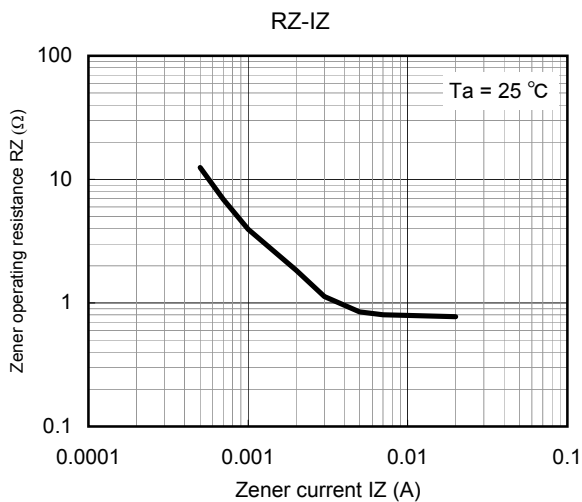
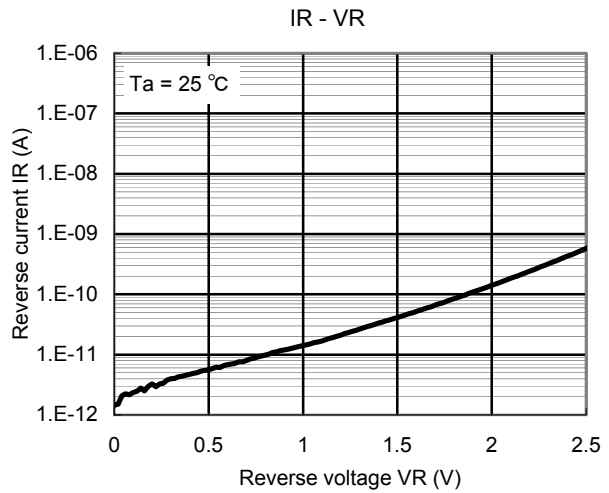
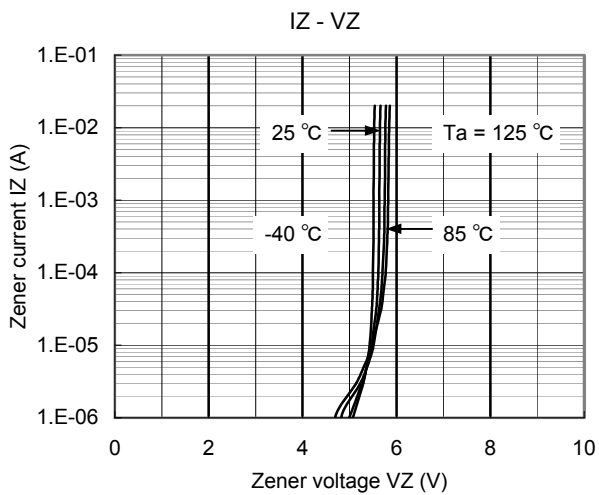
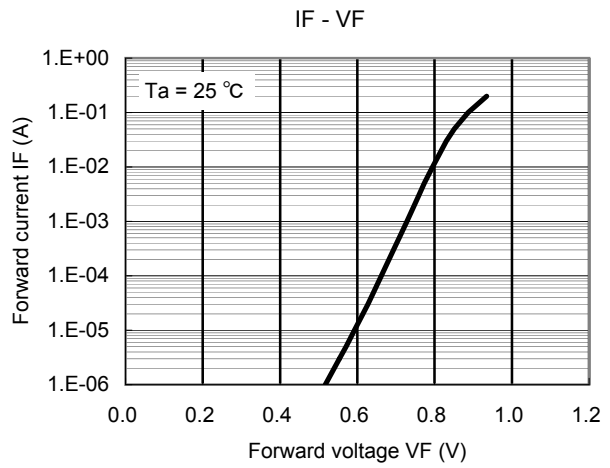
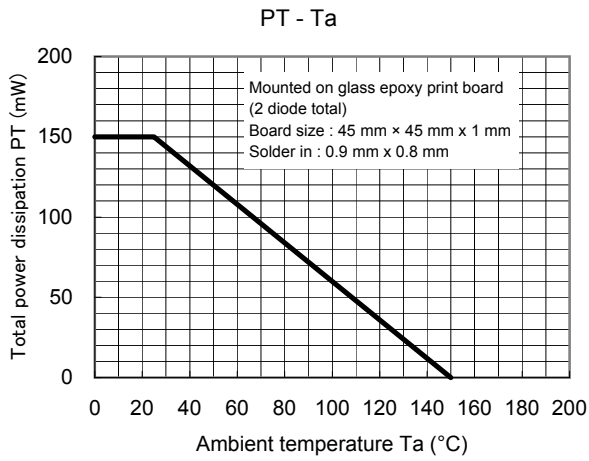
2. \*1: The temperature must be controlled 25°C for VZ measurement.

VZ value measured at other temperature must be adjusted to VZ (25°C)

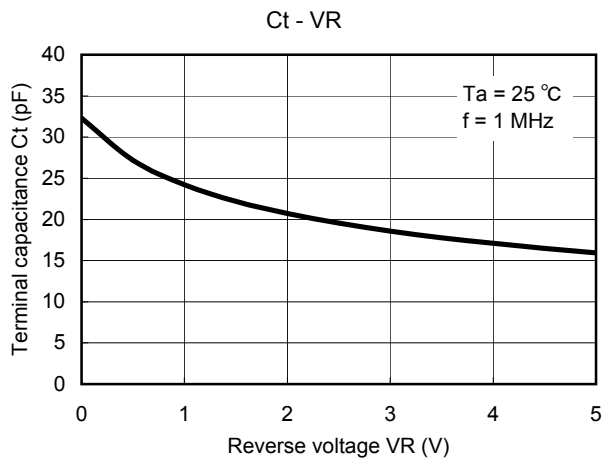
\*2: VZ guaranteed 20 ms after current flow.

\*3: T<sub>j</sub> = 25°C to 150°C

Technical Data ( reference )

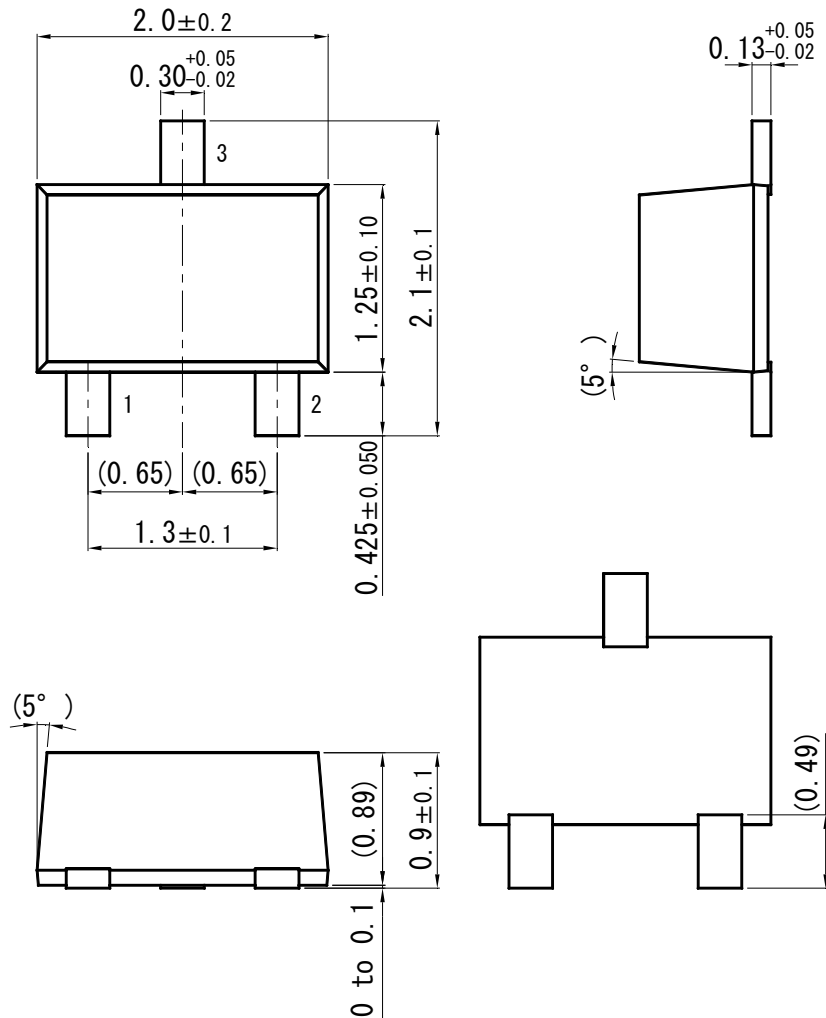


Technical Data ( reference )

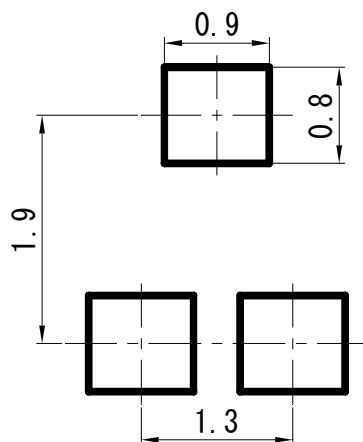


SMini3-F2-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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